Product End-of-Life Disassembly Instructions

Product Category: Monitor & Display
External Options

Marketing Name / Model
[List multiple models if applicable.]

HP HC271 Display

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>4</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[]”): [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain.</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>C605, C606 in SPS Board</td>
<td>2</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DP cable<em>1, HDMI cable</em>1, VGA cable<em>1, USB cable</em>1, Power cord*1</td>
<td>5</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs)</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

HPI instructions for this template are available at EL-MF877-01
### Item Description | Notes | Quantity of items included in product
--- | --- | ---
already listed as a separate item above) |  |  
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0  
Components and waste containing asbestos | 0  
Components, parts and materials containing refractory ceramic fibers | 0  
Components, parts and materials containing radioactive substances | 0  

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

| Tool Description | Tool Size (if applicable) |
--- | --- |
Screw driver |  |
Hexagon Screw Driver |  |
Diagonal cutting nippers |  |
Nosed pliers |  |
Knife |  |

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove ASSY RC by screw driver& hand.
2. Remove SHD USB by hand.
4. Remove Mylar& Unlock all screws in PCBA.
5. Disassemble PCBA from ASSY SHD & remove all wires.
6. Remove ASSY bezel by screw driver& hand.
7. Remove CTRL BD by hand.
8. Remove Brackets by screw driver& hand.
9. Remove panel from glass by knife& hand.
10. Remove privacy filter by hand.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Remove ASSY RC by screw driver& hand.

1.1 Unlock screws by screw driver.

1.2 Work in the hole with tool and along the top, right, & left side to separate ASSY RC.

2. Remove SHD USB by hand.

4. Remove Mylar & Unlock all screws in PCBA.

5. Disassemble PCBA from ASSY SHD & remove all wires.

6. Remove ASSY bezel by screw driver & hand.
7. Remove CTRL BD by hand.

![CTRL BD](image)

8. Remove Brackets by screw driver & hand.

8.1 remove BKT R/L by screw driver.

![Screw &4](image)

8.2 remove BKT T/B by hand.

![Screw &4](image)
9. Remove panel from glass by knife & hand.

10. Remove privacy filter by hand.